

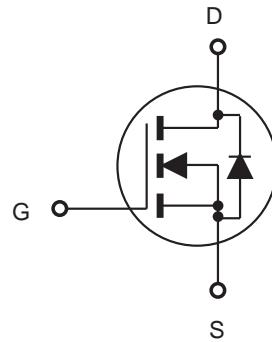
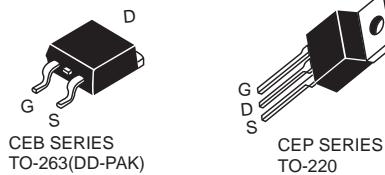


# CEP540A/CEB540A

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 100V, 36A,  $R_{DS(ON)} = 48m\Omega$  @  $V_{GS} = 10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- TO-220 & TO-263 package.



### ABSOLUTE MAXIMUM RATINGS

$T_C = 25^\circ C$  unless otherwise noted

| Parameter   | Symbol         | Limit       | Units              |
|---|----------------|-------------|--------------------|
| Drain-Source Voltage  | $V_{DS}$       | 100         | V                  |
| Gate-Source Voltage   | $V_{GS}$       | $\pm 20$    | V                  |
| Drain Current-Continuous  | $I_D$          | 36          | A                  |
| Drain Current-Pulsed <sup>a</sup>   | $I_{DM}$       | 120         | A                  |
| Maximum Power Dissipation @ $T_C = 25^\circ C$<br>- Derate above $25^\circ C$ | $P_D$          | 140<br>0.91 | W<br>W/ $^\circ C$ |
| Single Pulsed Avalanche Energy <sup>d</sup>                                   | $E_{AS}$       | 310         | mJ                 |
| Single Pulsed Avalanche Current <sup>d</sup>                                  | $I_{AS}$       | 18          | A                  |
| Operating and Store Temperature Range   | $T_J, T_{Stg}$ | -55 to 175  | $^\circ C$         |

### Thermal Characteristics

| Parameter                               | Symbol          | Limit | Units        |
|---|-----------------|-------|--------------|
| Thermal Resistance, Junction-to-Case    | $R_{\theta JC}$ | 1.1   | $^\circ C/W$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 62.5  | $^\circ C/W$ |



# CEP540A/CEB540A

**Electrical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

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| Parameter   | Symbol                     | Test Condition   | Min | Typ  | Max  | Units            |
|---|----------------------------|--|-----|------|------|------------------|
| <b>Off Characteristics</b>                                    |                            |  |     |      |      |                  |
| Drain-Source Breakdown Voltage                                | $\text{BV}_{\text{DSS}}$   | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$  | 100 |      |      | V                |
| Zero Gate Voltage Drain Current                               | $I_{\text{DSS}}$           | $V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$   |     |      | 25   | $\mu\text{A}$    |
| Gate Body Leakage Current, Forward                            | $I_{\text{GSSF}}$          | $V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$  |     |      | 100  | nA               |
| Gate Body Leakage Current, Reverse                            | $I_{\text{GSSR}}$          | $V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$   |     |      | -100 | nA               |
| <b>On Characteristics<sup>b</sup></b>                         |                            |  |     |      |      |                  |
| Gate Threshold Voltage  | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$  | 2   |      | 4    | V                |
| Static Drain-Source On-Resistance                             | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 18\text{A}$   |     | 40   | 48   | $\text{m}\Omega$ |
| <b>Dynamic Characteristics<sup>c</sup></b>                    |                            |  |     |      |      |                  |
| Forward Transconductance                                      | $g_{\text{FS}}$            | $V_{\text{DS}} = 25\text{V}, I_D = 18\text{A}$   |     | 14   |      | S                |
| Input Capacitance   | $C_{\text{iss}}$           | $V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$                           |     | 832  |      | pF               |
| Output Capacitance  | $C_{\text{oss}}$           |  |     | 240  |      | pF               |
| Reverse Transfer Capacitance                                  | $C_{\text{rss}}$           |  |     | 105  |      | pF               |
| <b>Switching Characteristics<sup>c</sup></b>                  |                            |  |     |      |      |                  |
| Turn-On Delay Time  | $t_{\text{d}(\text{on})}$  | $V_{\text{DD}} = 50\text{V}, I_D = 18\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 5.1\Omega$ |     | 13   | 40   | ns               |
| Turn-On Rise Time   | $t_r$                      |  |     | 11   | 35   | ns               |
| Turn-Off Delay Time   | $t_{\text{d}(\text{off})}$ |  |     | 32   | 65   | ns               |
| Turn-Off Fall Time  | $t_f$                      |  |     | 15   | 45   | ns               |
| Total Gate Charge   | $Q_g$                      | $V_{\text{DS}} = 80\text{V}, I_D = 18\text{A}, V_{\text{GS}} = 10\text{V}$                             |     | 37.5 | 48   | nC               |
| Gate-Source Charge  | $Q_{\text{gs}}$            |  |     | 6    |      | nC               |
| Gate-Drain Charge   | $Q_{\text{gd}}$            |  |     | 18   |      | nC               |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |                            |  |     |      |      |                  |
| Drain-Source Diode Forward Current                            | $I_S$                      |  |     |      | 36   | A                |
| Drain-Source Diode Forward Voltage <sup>b</sup>               | $V_{\text{SD}}$            | $V_{\text{GS}} = 0\text{V}, I_S = 18\text{A}$  |     |      | 1.3  | V                |

**Notes :**

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.
- d.L = 1.9mH,  $I_{AS} = 18\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

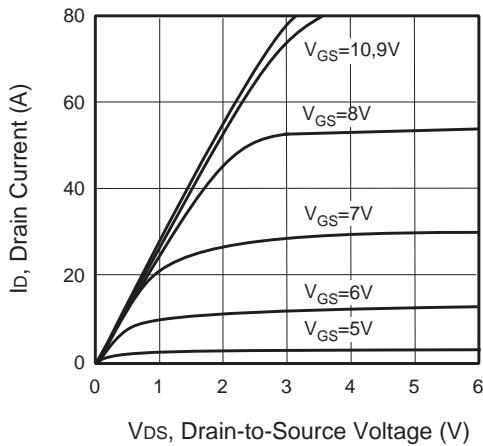


Figure 1. Output Characteristics

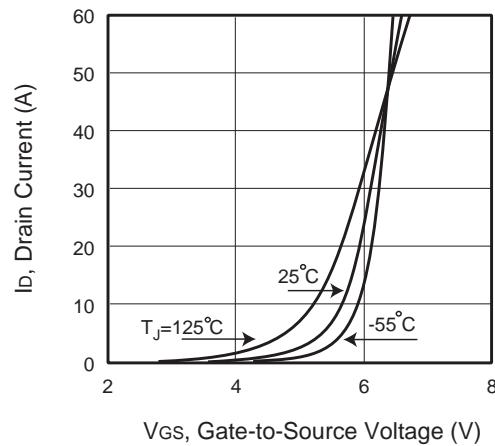


Figure 2. Transfer Characteristics

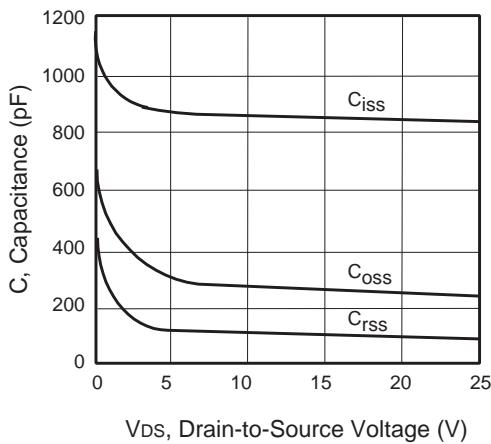


Figure 3. Capacitance

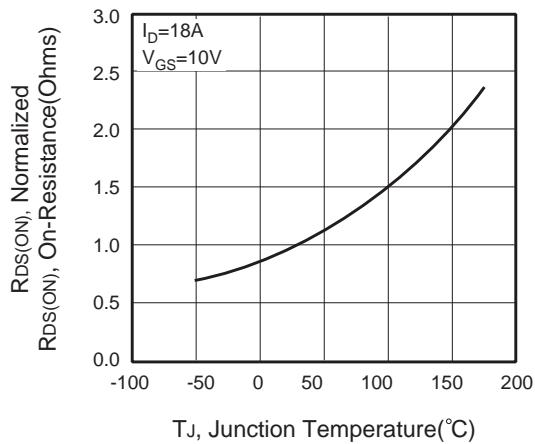


Figure 4. On-Resistance Variation with Temperature

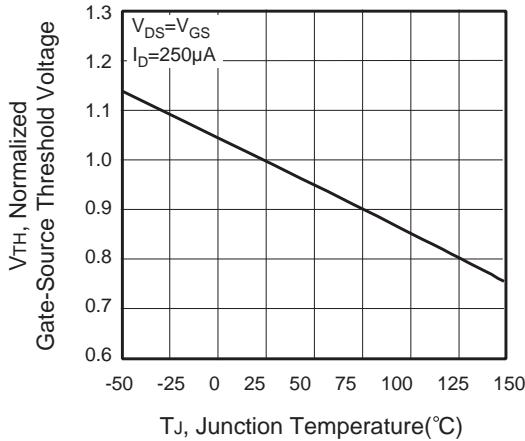


Figure 5. Gate Threshold Variation with Temperature

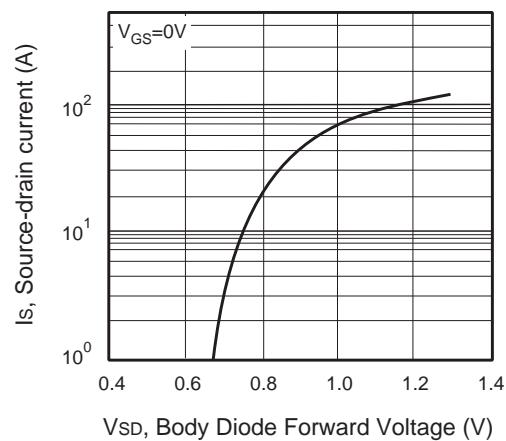
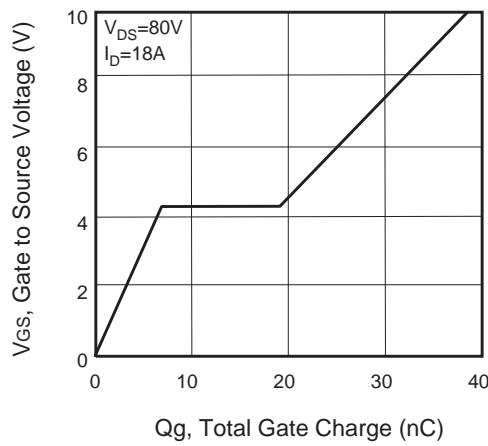
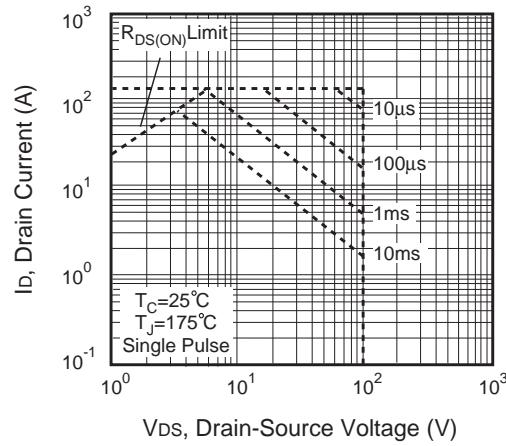


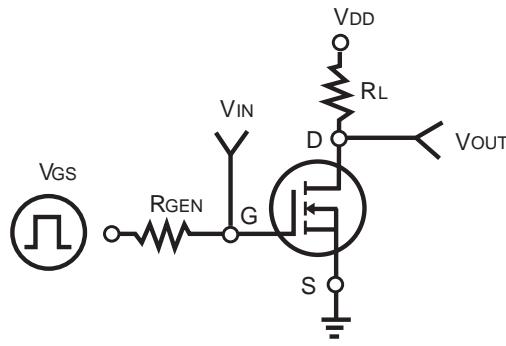
Figure 6. Body Diode Forward Voltage Variation with Source Current



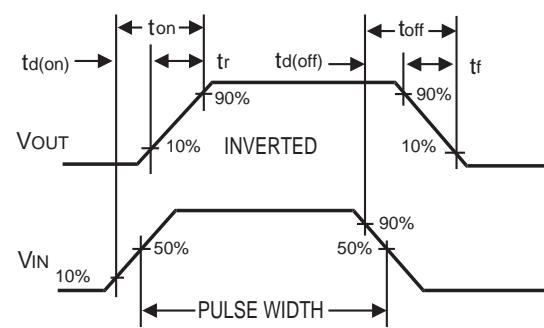
**Figure 7. Gate Charge**



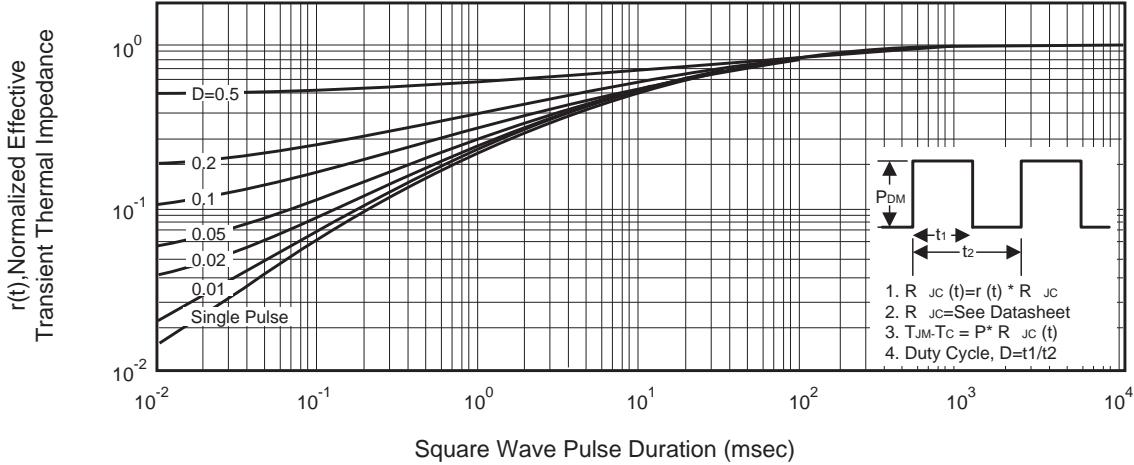
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**